IN THE CLAIMS

Please add claims 26 through 28, as follows:

1

2

3

5 .

1

2

3

2

- 1. (Original) A thin film transistor, comprising a source electrode, a drain electrode, a gate electrode, and a semiconductor layer, wherein one of the source electrode, the drain electrode, and the gate electrode comprises an aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed between the titanium and the aluminum-based layers.
- 2. (Original) The thin film transistor of claim 1, wherein the diffusion prevention layer and the titanium layer are orderly formed on opposite surfaces of the aluminum-based metal layer.
- 3. (Original) The thin film transistor of claim 1, wherein the diffusion prevention layer is a titanium nitride layer.
- 4. (Original) The thin film transistor of claim 3, wherein the titanium nitride layer contains 5 to 85 wt% of nitrogen.
- 5. (Original) The thin film transistor of claim 3, wherein the titanium nitride layer has a thickness of about 100 to 600Å.

6. (Original) The thin film transistor of claim 5, wherein the titanium nitride layer has a thickness of about 100 to 400Å.

1

2

1

2

1

2

1

2

4

1

2

1

- 7. (Original) The thin film transistor of claim 6, wherein the titanium nitride layer has a thickness of 200 to 400Å.
 - 8. (Original) The thin film transistor of claim 7, wherein the titanium nitride layer has a thickness of about 300Å.
 - 9. (Original) The thin film transistor of claim 1, wherein the aluminum-based metal layer is made of an aluminum alloy containing about 0.5 to 5 wt% of one element being selected from the group consisting of silicon, copper, neodymium, platinum, and nickel.
 - 10. (Original) The thin film transistor of claim 9, wherein the aluminum-based metal layer is made of an aluminum-silicon alloy containing about 2 wt% of silicon.
- 11. (Original) A flat panel display, comprising a plurality of sub-pixels driven by thin film transistors, each of the thin film transistors comprising a source electrode, a drain electrode, a gate electrode, and a semiconductor layer, wherein at least one of the 3

- source electrode, the drain electrode, and the gate electrode comprises an aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed
- between the aluminum-based metal layer and the titanium layer.

1

2

- 1 12. (Original) The flat panel display of claim 11, wherein the diffusion prevention layer and the titanium layer are orderly formed on opposite sides of the aluminum-based metal layer.
- 13. (Original) The flat panel display of claim 11, wherein the diffusion prevention layer is a titanium nitride layer.
- 14. (Original) The flat panel display of claim 13, wherein the titanium nitride layer contains 5 to 85 wt% of nitrogen.
 - 15. (Original) The flat panel display of claim 13, wherein the titanium nitride layer has a thickness of about 100 to 600Å.
- 16. (Original) The flat panel display of claim 15, wherein the titanium nitride layer has a thickness of about 100 to 400Å.
 - 17. (Original) The flat panel display of claim 16, wherein the titanium nitride

layer has a thickness of 200 to 400Å.

1

2

3

4

1

3

4

5

6

- 18. (Original) The flat panel display of claim 17, wherein the titanium nitride layer has a thickness of about 300Å.
 - 19. (Original) The flat panel display of claim 11, wherein the aluminum-based metal layer is made of an aluminum alloy containing about 0.5 to 5 wt% of one element being selected from the group consisting of silicon, copper, neodymium, platinum, and nickel.
- 20. (Original) The flat panel display of claim 19, wherein the aluminum-based metal layer is made of an aluminum-silicon alloy containing about 2 wt% of silicon.
 - 21. (Original) A flat panel display, comprising:
- driving circuits disposed along edges of said display;
 - a plurality of sub-pixels driven by thin film transistors; and
 - conductive lines connecting the driving circuits disposed along edges of said display to each of said plurality of sub-pixels, wherein said conductive lines comprise an aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed between the aluminum-based metal layer and the titanium layer.

- 22. (Original) The flat panel display of claim 21, wherein the diffusion prevention layer and the titanium layer are orderly formed on opposite sides of the aluminum-based metal layer.
- 23. (Original) The flat panel display of claim 21, wherein the diffusion prevention layer is a titanium nitride layer.
 - 24. (Original) The display of claim 23, said titanium nitride layer is 300 Å thick.
 - 25. (Original) The display of claim 24, said conductive lines being subjected to a heat treatment of 380°C.
 - 26. (New) A process for making a flat panel display, comprising:
- disposing driving circuits along edges of said display;

ì

2

3

1

1

2

1

4

5

6

7

- arranging a plurality of sub-pixels driven by thin film transistors; and
 - operatively connecting electrically conductive lines between the driving circuits disposed along edges of said display and each of said plurality of sub-pixels, wherein said conductive lines comprise an aluminum-based metal layer, a titanium layer, and a diffusion prevention layer interposed between the aluminum-based metal layer and the titanium layer.

- 27. (New) The process of claim 26, comprised of orderly forming the diffusion prevention layer and the titanium layer on opposite sides of the aluminum-based metal layer.
- 1 28. (New) The process of claim 26, wherein the diffusion prevention layer is a titanium nitride layer.